

Title (en)  
SELF-DISPERSING EPOXY RESINS AND COATINGS THEREFROM

Title (de)  
SELBSTDISPERGIERBARE EPOXYHARZZUSAMMENSETZUNGEN UND DEREN BESCHICHTUNGEN

Title (fr)  
RESINES EPOXYDES AUTO-DISPERSANTES ET REVETEMENTS EN ETANT FAITS

Publication  
**EP 0778856 A4 19971119 (EN)**

Application  
**EP 95929565 A 19950823**

Priority  

- US 9510422 W 19950823
- US 29978394 A 19940901
- US 45921095 A 19950602

Abstract (en)  
[origin: WO9606876A1] Self-dispersing curable epoxy resin dispersions prepared by a process comprising reducing the particle size of a mixture comprised of a self-dispersing curable epoxy resin based on a polyoxyalkyleneamine, water and an organic cosolvent and removing at least a major amount of said organic cosolvent from said mixture after said reducing, are provided. The self-dispersing curable epoxy resin is based on a polyoxyalkyleneamine. Thus, a polyoxyalkyleneamine was present as a chemical precursor of the epoxy resin or a starting material therefor. The self-dispersing curable epoxy resin of the invention is in the form of an aqueous dispersion. When cured, films of the self-dispersing curable epoxy resin dispersion are useful as a coating composition.

IPC 1-7  
**C08G 59/50**; **C08G 65/26**; **C08K 3/20**; **C08L 63/02**

IPC 8 full level  
**C08G 59/06** (2006.01); **C08G 59/10** (2006.01); **C08G 59/18** (2006.01); **C08G 59/22** (2006.01)

CPC (source: EP)  
**C08G 59/06** (2013.01); **C08G 59/10** (2013.01); **C08G 59/184** (2013.01); **C08G 59/226** (2013.01)

Citation (search report)  

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- [PY] WO 9501387 A1 19950112 - HENKEL CORP [US] & US 5565505 A 19961015 - PAPALOS JOHN G [US], et al
- [DPY] WO 9518165 A1 19950706 - HENKEL CORP [US]
- [PY] WO 9518167 A1 19950706 - HENKEL CORP [US] & US 5604269 A 19970218 - PAPALOS JOHN G [US], et al
- See references of WO 9606876A1

Designated contracting state (EPC)  
DE DK FR GB IT

DOCDB simple family (publication)  
**WO 9606876 A1 19960307**; EP 0778856 A1 19970618; EP 0778856 A4 19971119

DOCDB simple family (application)  
**US 9510422 W 19950823**; EP 95929565 A 19950823